

Application No. 09/512,223

Docket No. 104142

APPENDIX

Changes to Claims:

The following are marked-up versions of the amended claims 1 and 6:

1. (Twice Amended) An electrical circuit comprising an integrated circuit, an antenna and one or more electrical connections between the integrated circuit and the antenna, wherein at least the integrated circuit and the antenna are encapsulated within a capsule such that the capsule mechanically connects the integrated circuit and the antenna to hold the integrated circuit and the antenna in a fixed position relative to each other, and wherein the capsule comprises a thermoplastic resin having a melting point of from 120°C to 250°C and a processing pressure of from 5 to 40 bar.

6. (Twice Amended) Transponder comprising an electrical circuit containing at least one component suitable for interaction with an electromagnetic field encapsulated within a capsule, wherein the capsule comprises a thermoplastic resin having a melting point of from 120°C to 250°C and a processing pressure of from 5 to 40 bar, and wherein the electrical circuit is encapsulated by the thermoplastic resin such that at least an integrated circuit and an antenna of the electrical circuit are encapsulated by the thermoplastic resin and are mechanically connected by the thermoplastic resin to hold the integrated circuit and the antenna in a fixed position relative to each other.